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半导体激光在下颌第三磨牙拔除术后并发症预防的应用进展

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Effectiveness of semiconductor laser irradiation in the prevention of postoperati

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摘要

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**摘要** 下颌阻生第三磨牙拔除术是牙槽外科一项较为复杂的手术。其术后的主要并发症为拔牙后疼痛、面部肿胀反应、感染、干槽症、拔牙术后出血、颞下颌关节紊乱综合征和开口受限等。半导体激光器发展至今，在诸多领域中都得到了广泛应用。本文通过对激光生物学效应的探讨，对半导体激光在下颌第三磨牙拔除术后并发症预防方面的作用作一综述。

**关键词：** 半导体激光 下颌第三磨牙 并发症

**Abstract:** The extraction of mandibular third tooth is a complicated operation in alveolar surgery. The main complications are pain, swelling, infection, dry socket, bleeding, temporomandibular joint disorders and restrict opening. Semiconductor laser is widely used in a good many fields. The review discusses the mechanism of semiconductor laser and summarizes effectiveness in the prevention of postoperative complication after mandibular third tooth extraction.

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